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U.S.

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10025144	FILING DATE 12/18/2001	CLASS 438	SUBCLASS 633	CAU 2815	EXAMINER <i>Amot</i>
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APPLICANTS: Moon Yongsik; Mai David; Wijekoon Kapitz; Bajaj Rajeev; Surana Rajul; Hu Yongqi; Kaushal Tony; Li Shijian; Li Jui-Lung; Wang Shi-Ping; Lam Gary; Reiser Frank;

CONTINUING DATA VERIFIED: *J.W.B.*
THIS APPLN CLAIMS BENEFIT OF 80/304,543 07/11/2001

FOREIGN APPLICATIONS VERIFIED: *None J.W.B.*

PG-FEE DO NOT PUBLISH ☐ RESCIND ☐

Foreign priority claimed ☐ yes ☒ no
USPC 119 conditions met ☐ yes ☒ no
Verified that Acknowledged Inventors's initials *J.W.B.*

ATTORNEY DOCKET NO. MAT/5803/CMP/CMP/RKK

TITLE: *Method and apparatus for polishing metal and electronic substrates*

U.S. DEPT. OF COM. PAT. & TM. PTO-326 (Rev. 12-00)

NOTICE OF ALLOWANCE M.

7/29/03

ISSUE FEE

Amount Due: *\$1600* Date Paid

☐ TERMINAL DISCLAI

DRAWINGS			CLAIMS ALLOWED	
Sheets Drawg.	Figs. Drawg.	Print Fig.	Total Claims	Print Claim for O.G.
(Assistant Examiner) (Date) (Primary Examiner) (Date) (Legal Representative Examiner) (Date)			NOTICE OF ALLOWANCE MAILED	
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